

## 具有精密电压基准的仪表放大器

### 特性

- 低静态电流
- 休眠模式
- 精密电压基准
- 低偏移电压
- 低偏移漂移
- 低输入偏置电流
- 高共模抑制 (CMR)
- 低噪声
- 输入保护
- 宽电源电压

### 应用范围

- 压力和温度桥式放大器
- 工业过程控制
- 工厂自动化
- 多通道数据采集
- 电池供电系统
- 通用仪表

### 说明

INA125 是一款具有一个精密电压基准的低功耗、高精度仪表放大器。它在一个单集成电路上提供完整的桥式激励和精密差分输入放大。

使用引脚可选电压可从外部调节电压基准，从而实现多种变换器的使用。休眠模式可实现关断和占空比操作以节约能耗。

### ORDERING INFORMATION<sup>(1)</sup>

PRODUCT	PACKAGE DESIGNATOR	PACKAGE	ORDERABLE PART NUMBER	PACKAGE QUANTITY
INA125	TD	Bare die in waffle pack <sup>(2)</sup>	INA125TDA1	112
			INA125TDA2	10

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at [www.ti.com](http://www.ti.com).

(2) Processing is per the Texas Instruments commercial production baseline and is in compliance with the Texas Instruments Quality Control System in effect at the time of manufacture. Electrical screening consists of DC parametric and functional testing at room temperature only. Unless otherwise specified by Texas Instruments AC performance and performance over temperature is not warranted. Visual Inspection is performed in accordance with MIL-STD-883 Test Method 2010 Condition B at 75X minimum.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

**BARE DIE INFORMATION**

DIE THICKNESS	BACKSIDE FINISH	BACKSIDE POTENTIAL	BOND PAD METALLIZATION COMPOSITION	BOND PAD THICKNESS
10.5 mils.	Silicon with backgrind	Floating	AlCu (0.5%)	1100 nm



**Table 1. Bond Pad Coordinates in Microns**

DESCRIPTION	PAD NUMBER	X MIN	Y MIN	X MAX	Y MAX
V+	1	-2019.3	-335.2	-1917.7	-233.68
SLEEP	2	-2019.3	-538.48	-1917.7	-436.88
V-	3	-1816.1	-838.2	-1714.5	-736.6
VREFOUT	4	-365.76	-820.42	-264.16	-718.82
IAREF	5	-60.96	-820.42	106.68	-718.82
VIN+	6	673.1	-820.42	774.7	-718.82
VIN-	7	1889.76	-652.78	1991.36	-551.18
RG	8	1897.38	-429.26	1998.98	-327.66
RG	9	1823.72	307.34	1925.32	408.94
VO	10	1892.3	515.62	1993.32	617.22
Sense	11	764.54	718.82	932.18	820.42
VREFCOM	12	393.7	718.82	561.34	820.42
N/C	13	-878.84	718.82	-777.24	820.42
VREFBG	14	-1094.74	713.74	-993.14	815.34
VREF2.5	15	-1544.32	718.82	-1442.72	820.42
VREF5	16	-2001.52	467.36	-1899.92	568.96
VREF10	17	-2001.52	243.84	-1899.92	345.44

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
INA125TDA1	ACTIVE			0	112	RoHS & Green	Call TI	N / A for Pkg Type			Samples
INA125TDA2	ACTIVE			0	10	RoHS & Green	Call TI	N / A for Pkg Type			Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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